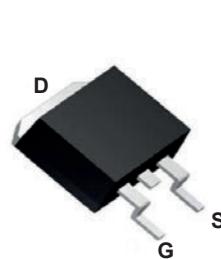
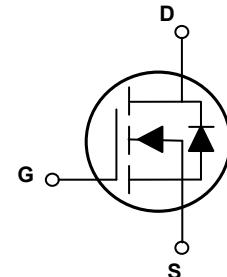


## Main Product Characteristics

$BV_{DSS}$	800V
$R_{DS(ON)}$	115mΩ (Typ.)
$I_D$	27A



TO-263



Schematic Diagram

## Features and Benefits

- Advanced MOSFET process technology
- Ideal for high efficiency switched mode power supplies
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



## Description

The GSJT8027 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supplies and a wide variety of other applications.

## Absolute Maximum Ratings ( $T_C=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain-Source Voltage ( $V_{GS}=0\text{V}$ )	$V_{DS}$	800	V
Gate-Source Voltage ( $V_{DS}=0\text{V}$ ) AC ( $f>1\text{Hz}$ )	$V_{GS}$	±30	V
Gate-Source Voltage ( $V_{DS}=0\text{V}$ ) DC		±20	V
Continuous Drain Current at $T_c=25^\circ\text{C}$	$I_D$	27	A
Continuous Drain Current at $T_c=100^\circ\text{C}$		18.9	A
Pulsed Drain Current <sup>1</sup>	$I_{DM}$	81	A
Maximum Power Dissipation ( $T_c=25^\circ\text{C}$ )	$P_D$	316	W
Derate Above $25^\circ\text{C}$		2.1	W/ $^\circ\text{C}$
Avalanche Current <sup>2</sup>	$I_{AS}$	4	A
Drain Source Voltage Slope, $V_{DS}\leq 480\text{V}$	$dv/dt$	50	V/ns
Reverse Diode $dv/dt$ , $V_{DS}\leq 480\text{V}$ , $I_{SD} < I_D$	$dv/dt$	50	V/ns
Max. Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	0.27	$^\circ\text{C}/\text{W}$
Max. Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	62	$^\circ\text{C}/\text{W}$
Operating Junction and Storage Temperature Range	$T_J/T_{STG}$	-55 to +175	$^\circ\text{C}$

**Electrical Characteristics** ( $T_A=25^\circ\text{C}$  unless otherwise specified)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>On / Off Characteristics</b>						
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=1\text{mA}$	800	-	-	V
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}}=800\text{V}, V_{\text{GS}}=0\text{V}, T_c=25^\circ\text{C}$	-	-	10	$\mu\text{A}$
Zero Gate Voltage Drain Current		$V_{\text{DS}}=800\text{V}, V_{\text{GS}}=0\text{V}, T_c=125^\circ\text{C}$	-	-	500	
Gate-Body Leakage Current	$I_{\text{GSS}}$	$V_{\text{GS}}=\pm 20\text{V}, V_{\text{DS}}=0\text{V}$	-	-	$\pm 100$	nA
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=1\text{mA}$	3.5	4.2	5.0	V
Drain-Source On-State Resistance	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=13\text{A}$	-	115	140	$\text{m}\Omega$
<b>Dynamic and Switching Characteristics</b>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}}=50\text{V}, V_{\text{GS}}=0\text{V}, F=1.0\text{MHz}$	-	3300	3800	pF
Output Capacitance	$C_{\text{oss}}$		-	116	-	
Reverse Transfer Capacitance	$C_{\text{rss}}$		-	2.9	-	
Total Gate Charge	$Q_g$	$V_{\text{DS}}=600\text{V}, I_{\text{D}}=14\text{A}, V_{\text{GS}}=10\text{V}$	-	61	66	nC
Gate-Source Charge	$Q_{\text{gs}}$		-	16.6	-	
Gate-Drain Charge	$Q_{\text{gd}}$		-	17.6	-	
Gate Plateau Voltage	$V_{\text{gp}}$		-	5.1	-	
Intrinsic Gate Resistance	$R_g$	$F=1\text{MHz}$ open drain	-	2.0	-	$\Omega$
Turn-on Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}}=380\text{V}, I_{\text{D}}=14\text{A}, R_{\text{G}}=1.7\Omega, V_{\text{GS}}=10\text{V}$	-	16	-	nS
Turn-on Rise Time	$t_r$		-	6	-	
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$		-	60	-	
Turn-Off Fall Time	$t_f$		-	3	-	
<b>Source-Drain Ratings and Characteristics</b>						
Source-Drain Current (Body Diode)	$I_{\text{SD}}$	$T_c=25^\circ\text{C}$	-	-	27	A
Pulsed Source-Drain Current (Body Diode)	$I_{\text{SDM}}$		-	-	81	A
Forward On Voltage	$V_{\text{SD}}$	$T_j=25^\circ\text{C}, I_{\text{SD}}=27\text{A}, V_{\text{GS}}=0\text{V}$	-	0.9	1.2	V
Reverse Recovery Time	$T_{\text{rr}}$	$T_j=25^\circ\text{C}, I_{\text{F}}=14\text{A}, \frac{di}{dt}=100\text{A}/\mu\text{s}$	-	180	-	nS
Reverse Recovery Charge	$Q_{\text{rr}}$		-	1.30	-	uC
Peak Reverse Recovery Current	$I_{\text{rrm}}$		-	14	-	A

Note:

1. Repetitive rating: Pulse width limited by maximum junction temperature.
2.  $T_j=25^\circ\text{C}, V_{\text{DD}}=50\text{V}, V_{\text{G}}=10\text{V}, R_{\text{G}}=25\Omega$ .

## Typical Electrical and Thermal Characteristic Curves

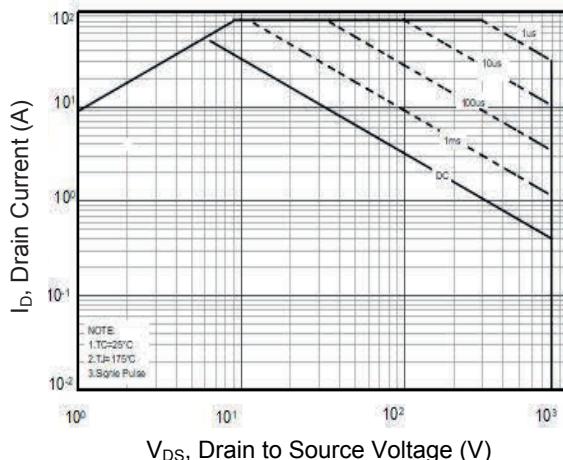


Figure 1. Safe Operation Area

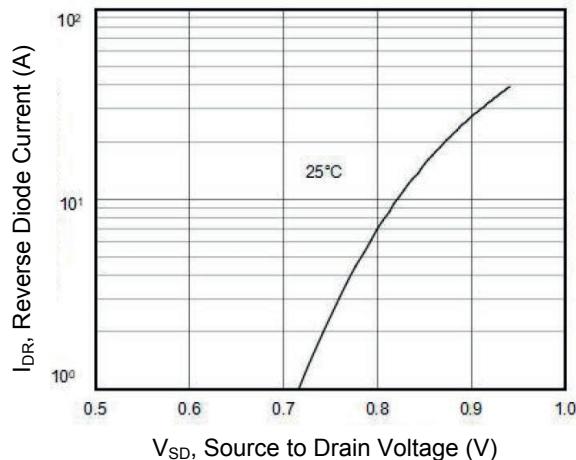


Figure 2. Source-Drain Diode Forward Voltage

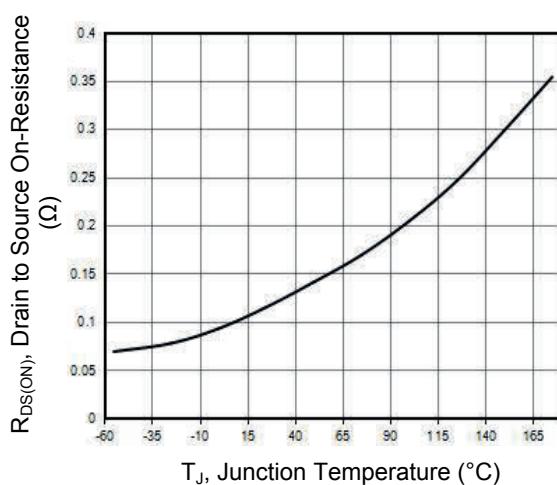


Figure 3.  $R_{DS(ON)}$  vs. Junction Temperature

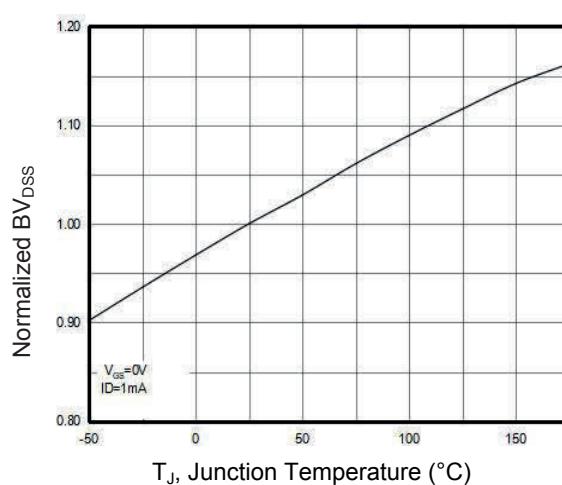


Figure 4.  $BV_{DSS}$  vs.  $T_J$

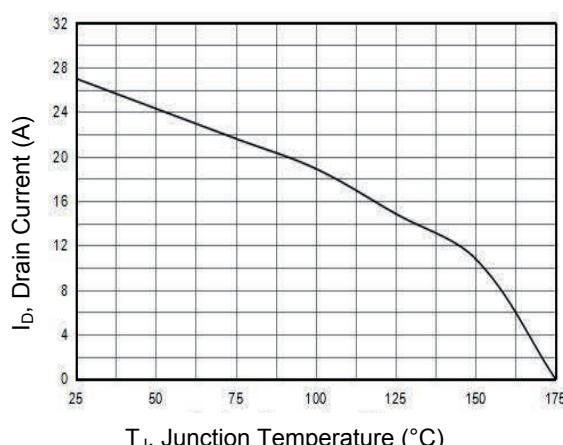


Figure 5. Maximum  $I_D$  vs.  $T_J$

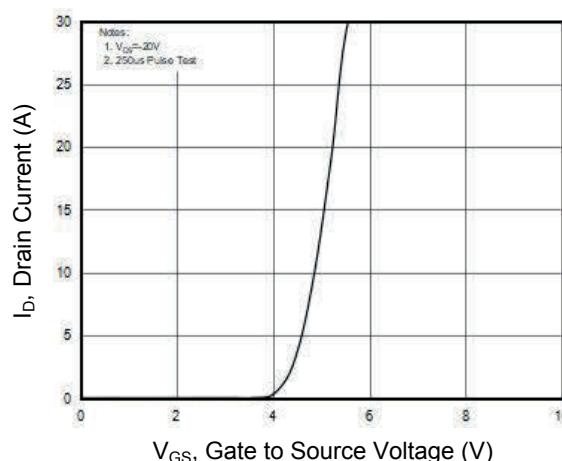


Figure 6. Transfer Characteristics

## Typical Electrical and Thermal Characteristic Curves

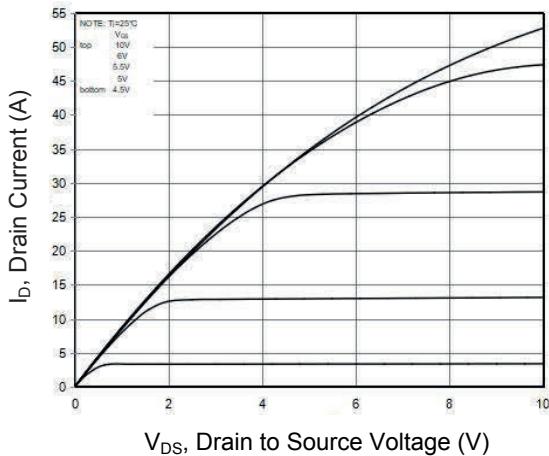


Figure 7. Output Characteristics

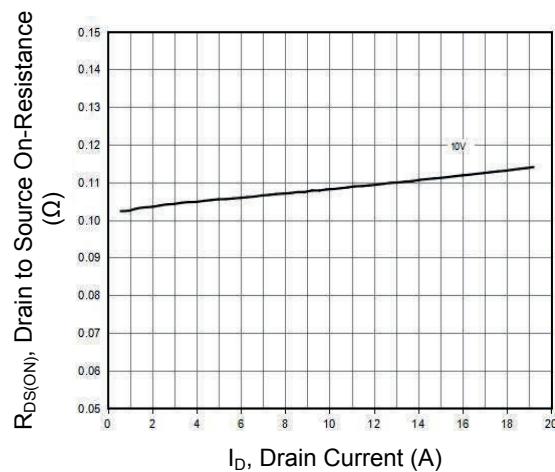


Figure 8. Static Drain-Source On Resistance

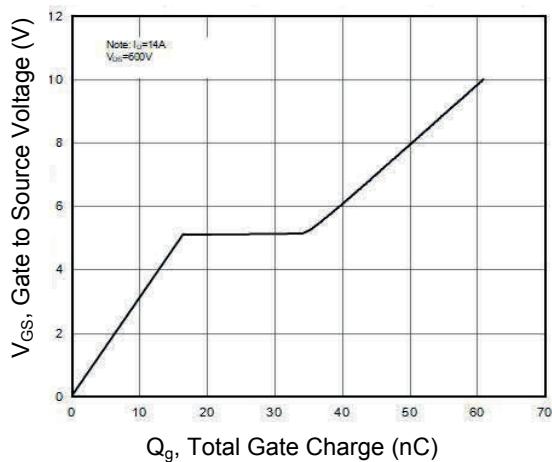


Figure 9. Gate Charge Waveforms

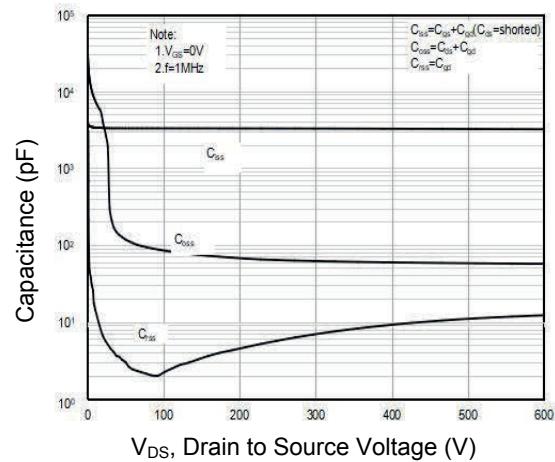
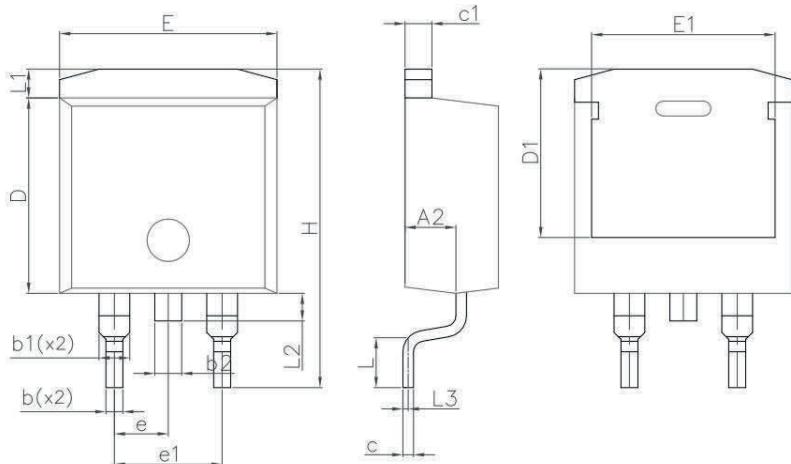


Figure 10. Capacitance

### Package Outline Dimensions (TO-263)



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	4.20	4.60	0.165	0.181
A1	0.00	0.25	0.00	0.010
A2	2.20	2.60	0.087	0.102
b	0.70	0.90	0.028	0.035
b1	1.20	1.75	0.047	0.069
b2	1.17	1.37	0.046	0.054
c	0.40	0.60	0.016	0.024
c1	1.15	1.40	0.045	0.055
D	9.10	9.30	0.358	0.366
D1	7.63	8.23	0.300	0.324
E	10.05	10.45	0.396	0.411
E1	8.35	8.95	0.329	0.352
e	2.54 BSC		0.100 BSC	
e1	5.08 BSC		0.200 BSC	
H	14.61	15.88	0.575	0.625
L	1.78	2.79	0.070	0.110
L1	1.36 REF		0.054 REF	
L2	1.30 REF		0.05 1REF	

### Order Information

Device	Package	Marking	Carrier	Quantity
GSJT8027	TO-263	JT8027	Tape & Reel	800 pcs / Reel

For more information, please contact us at: [inquiry@goodarksemi.com](mailto:inquiry@goodarksemi.com)